

# **Gas Discharge Tubes** SL1010A Series

**Electrical Characteristics** 

Part Number	DC ii	Breakd n Volts¹ @ 100V/	lown , <sub>2,3</sub> /s)	Impulse Breakdown in Volts <sup>2,3</sup> (@100V/ µs)	Impulse Breakdown In Volts <sup>2,3</sup> (@1kV/μs)	Insulation Resistance	Capacitance (@1MHz 0V Bias)	Arc Voltage (on state Voltage) @1Amp Min	Nominal Impulse Discharge Current (x10@8/20µs)	Nominal Impulse Discharge Current (x1@10/350µs)
	MIN	ТҮР	MAX	MAX		MIN	MAX			
SL1010A075	60	75	90	450	600	>1GΩ (at 50VDC)	<1.5 pF	~10 V	5kA	1kA
SL1010A090	72	90	108	- 550	700					
SL1010A170	136	170	204							
SL1010A230	184	230	276	580	750					
SL1010A350	280	350	420	850	1000					
SL1010A420	335	420	504	650	850					
SL1010A470	376	470	564	800	950					

0,4 ± 0,05

±0,2

Ø5 :

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#### Notes:

1. At delivery AQL 0.65 level II, DIN ISO 2859

2. In ionized mode, tested according to ITU-T Rec. K.12

3. Comparable to the silicon measurement Switching Voltage (Vs)

4. Total current through center electrode at 10kA, through side electrode respectively at 5kA

#### **Product Characteristics**

	Construction: Ceramic Insulator		
Materials	Device Finish: Dull Tin-plated		
	17.5 +/- 12.5 microns		
Product Marking	Littelfuse 'LF' Mark, voltage and date code		

Glow to Arc Transition Current	~1 Amp
Glow Voltage	~60 Volts
Storage and Operational Temperature	-40 to +90°C

### **Device Dimensions**

#### For SL1010A series:



# For SL1010A series failsafe version:





7,6 ± 0,2

tin-plated

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Ø4,7

1,6 ± 0,1

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recommended pad outline

2.8 S

recommended pad outline

Dimensions are in millimeters [and inches]



#### Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Cond	lition	Pb-free assembly		
	- Temperature Min (T <sub>s(min)</sub> )	150°C		
Pre Heat	- Temperature Max (T <sub>s(max)</sub> )	200°C		
	-Time (Min to Max) (t <sub>s</sub> )	60 – 180 seconds		
Average Ram to peak)	ոթ-up Rate (Liquidus Temp (T <sub>լ</sub> )	3°C/second max.		
$T_{S(max)}$ to $T_L$ - I	Ramp-up Rate	5°C/second max.		
Poflow	- Temperature (T <sub>L</sub> ) (Liquidus)	217°C		
nellow	- Temperature (t <sub>L</sub> )	60 – 150 seconds		
Peak Tempera	ature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C		
Time within (t <sub>p</sub> )	5°C of Actual Peak Temperature	10 – 30 seconds		
Ramp-down	Rate	6°C/second max.		
Time 25°C to	Peak Temperature (T <sub>P</sub> )	8 minutes max.		
Do not excee	d	260°C		



#### Soldering Parameters - Hand Soldering

Solder Iron Temperature: 350° C +/- 5°C Heating Time: 5 seconds max.

#### Packaging

'SM' Type Surface Mount Items: Packaged tape and reel carrier, 900 pcs/reel (specifications below)



### Part Numbering System and Ordering Information





# Voltage –

### Pin Configuration -

F = with Failsafe (Packed in carrier and tape, 900pcs/reel)

SM = Surface Mount (Packed in carrier and tape, 900pcs/reel)

SMF = Surface Mount with Failsafe (Packed in carrier and tape, 900pcs/reel)

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